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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/038,334	10/18/2001	Ashay A. Dani	042390.P12141	7280
75	90 02/24/2004		EXAM	INER
Stephen M. De Klerk			AHMED, SHEEBA	
BLAKELY, SO	BLAKELY, SOKOLOFF, TAYLOR & ZAFMAN LLP			PAPER NUMBER
Seventh Floor			ART UNIT	FAFER NOWBER
12400 Wilshire Boulevard			1773	
Los Angeles, CA 90025-1026			DATE MAILED: 02/24/2004	

Please find below and/or attached an Office communication concerning this application or proceeding.

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·	Application No.	Applicant(s)	
	10/038,334	DANI ET AL.	
Office Action Summary	Examiner	Art Unit	
	Sheeba Ahmed	1773	
The MAILING DATE of this communication app Period for Reply	ears on the cover sheet	with the correspondence address	
A SHORTENED STATUTORY PERIOD FOR REPLY THE MAILING DATE OF THIS COMMUNICATION. - Extensions of time may be available under the provisions of 37 CFR 1.13 after SIX (6) MONTHS from the mailing date of this communication. - If the period for reply specified above is less than thirty (30) days, a reply - If NO period for reply is specified above, the maximum statutory period v - Failure to reply within the set or extended period for reply will, by statute, Any reply received by the Office later than three months after the mailing earned patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may within the statutory minimum of the vill apply and will expire SIX (6) Marcause the application to become	a reply be timely filed hirty (30) days will be considered timely. ONTHS from the mailing date of this communic ABANDONED (35 U.S.C. § 133).	cation.
Status			
1) Responsive to communication(s) filed on 04 N	<u>ovember 2003</u> .		
24/23	action is non-final.		
3) Since this application is in condition for allowar			ts is
closed in accordance with the practice under E	x parte Quayle, 1955 C	5.D. 11, 403 O.G. 213.	
Disposition of Claims			
4) Claim(s) 1-13 and 15-30 is/are pending in the 4a) Of the above claim(s) is/are withdraw 5) Claim(s) is/are allowed. 6) Claim(s) 1-13 and 15-30 is/are rejected. 7) Claim(s) is/are objected to. 8) Claim(s) are subject to restriction and/o	wn from consideration.		
Application Papers	·		
9)☐ The specification is objected to by the Examine	er.		
10)☐ The drawing(s) filed on is/are: a)☐ acc			
Applicant may not request that any objection to the			04(4)
Replacement drawing sheet(s) including the correct 11) The oath or declaration is objected to by the Ex			
Priority under 35 U.S.C. § 119			•
12) Acknowledgment is made of a claim for foreign a) All b) Some * c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority document application from the International Burea * See the attached detailed Office action for a list	s have been received. s have been received in rity documents have be u (PCT Rule 17.2(a)).	n Application No en received in this National Stag	e
Attachment(s) 1) Notice of References Cited (PTO-892) 2) Notice of Draftsperson's Patent Drawing Review (PTO-948) 3) Information Disclosure Statement(s) (PTO-1449 or PTO/SB/08) Paper No(s)/Mail Date	Paper	w Summary (PTO-413) No(s)/Mail Date of Informal Patent Application (PTO-152)	

U.S. Patent and Trademark Office PTOL-326 (Rev. 1-04) Application/Control Number: 10/038,334

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DETAILED ACTION

Response to Amendment

Amendments to claim 1 have been added in the above-identified application.
 Claim 14 has been cancelled. Claims 1-13 and 15-30 are pending.

Claim Rejections - 35 USC § 103

The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

- (a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negatived by the manner in which the invention was made.
- 2. Claims 1-13 and 15-30 are rejected under 35 U.S.C. 103(a) as being unpatentable over Huang et al. (US 5,062,896) in view of Hanrahan (US 5,945,217).

Huang et al. disclose interconnection materials for forming connections between electroconductive members (Column 1, lines 6-10) and comprising metal alloy powder and polymer paste wherein the polymer is heat softenable above the melting temperature of the metal solder particle filler (Column 1, lines 43-53). The preferred compositions comprise polyimide siloxane binder material and bismuth-tin alloys having a melting temperature in the area of 138°C (Column 1, lines 67-68, Column 2, lines 1-10 and Column 3, lines 30-34). The composition comprises between 85 and 95% by weight of metal alloy powder (Column 3, lines 15-20).

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Huang et al. do not specifically state that metal alloy powder/polymer paste further comprises filler particles or that the size of the bismuth-tin alloy particles is between 0.2 and 100 microns.

However, Hanrahan discloses a thermally conductive article comprising a matrix material with thermally conductive particles and a phase change material wherein preferred thermally conductive particles include Al, Cu, Nl, Ag, or Zn (Column 2, lines 31-45). Hanrahan's thermally conductive article can be mounted between a heat sink and an integrated circuit device and provides an interface with exceptional conformability between the component parts (Column 3, lines 33-40). The thermally conductive particles can be present in proportions of at least 20 to 99 weight percent (Column 4, lines 36-45).

Accordingly, it would have been obvious to one having ordinary skill in the art to add thermally conductive particles, such as Al particles, to the metal alloy powder/polymer paste taught by Huang et al. given that Hanrahan specifically teach that such particles increase the thermal conductivity of the material and provide an interface with exceptional conformability between the component parts. Furthermore, it would have been obvious to one having ordinary skill in the art to optimize the size of the bismuth-tin alloy particles given that the size of the solder particles would affects the rate of melting of these particles.

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Response to Arguments

3. Applicant's arguments with respect to claims 1-13 and 15-30 have been considered but are moot in view of the new ground(s) of rejection.

Conclusion

4. Any inquiry concerning this communication or earlier communications from the examiner should be directed to Sheeba Ahmed whose telephone number is (571)272-1504. The examiner can normally be reached on Mondays and Thursdays from 8am-6pm.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Paul Thibodeau can be reached on (571)272-1516. The fax phone number for the organization where this application or proceeding is assigned is 703-872-9306.

Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).

Sheeba Ahmed

February 19, 2004